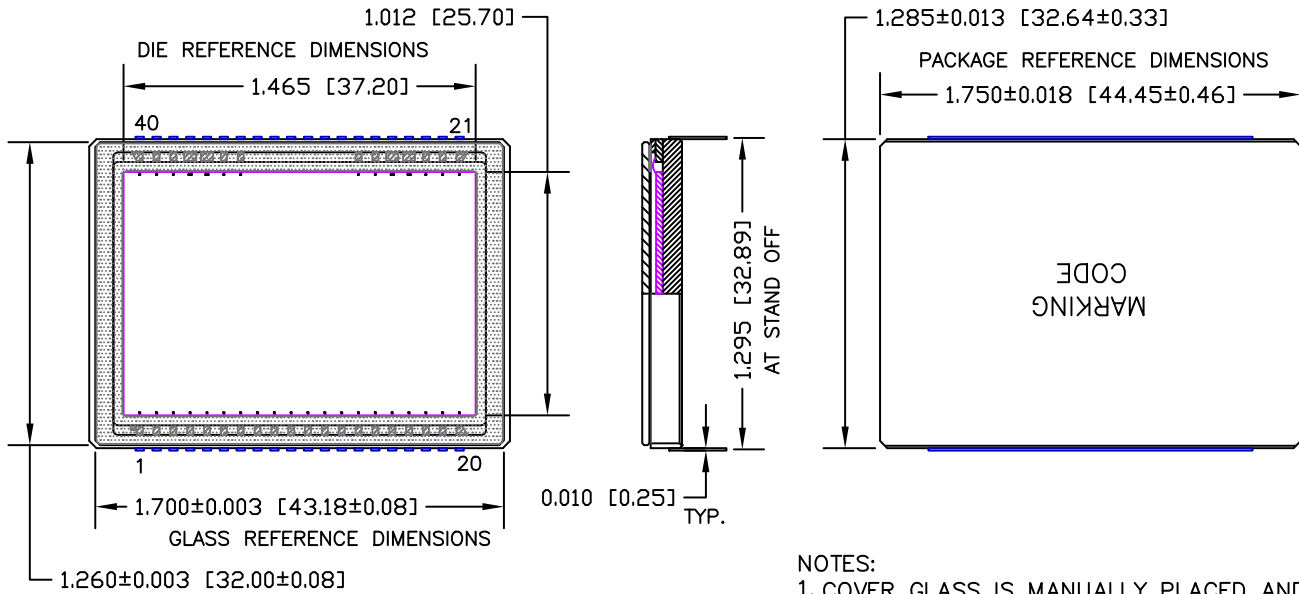


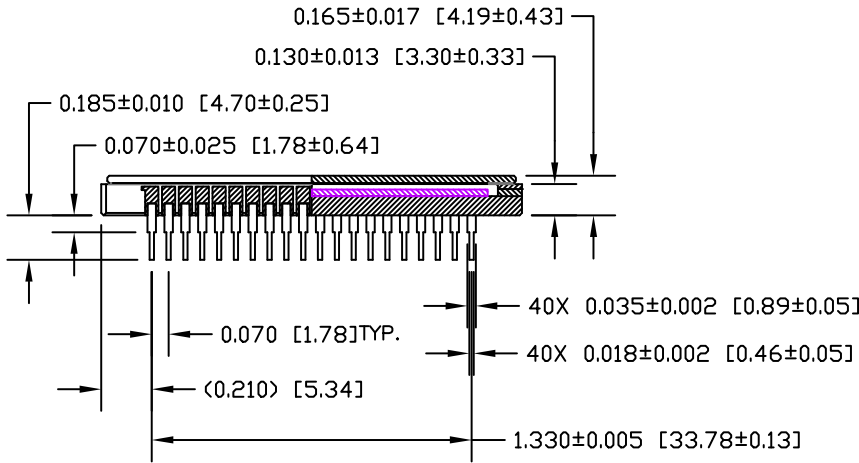
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

CERAMIC DIP 40, 44.45x32.64
CASE 125BM
ISSUE O

DATE 03 JUL 2014



NOTES:
 1. COVER GLASS IS MANUALLY PLACED AND VISUALLY ALIGNED OVER DIE – LOCATION ACCURACY IS NOT GUARANTEED.

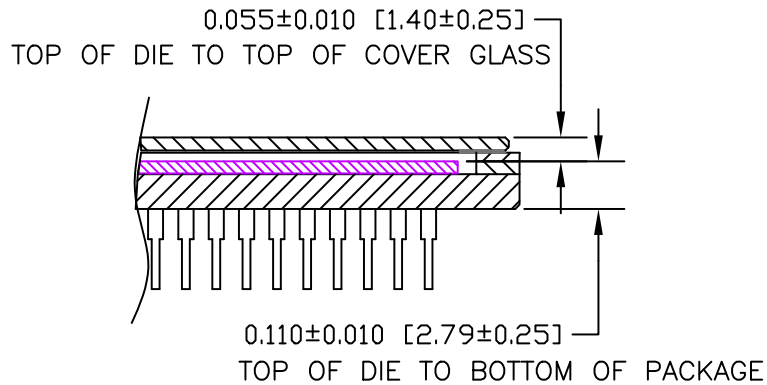
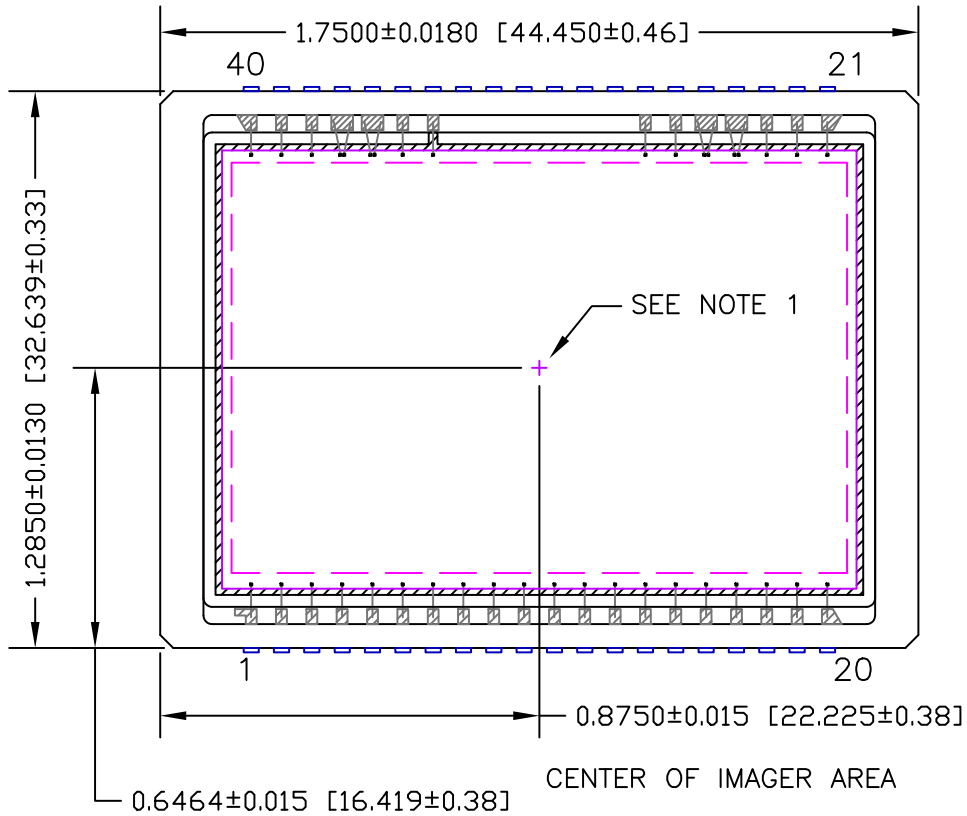


Dimensions in: Inches [mm]

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CERAMIC DIP 40, 44.45x32.64
CASE 125BM
ISSUE O

DATE 03 JUL 2014



NOTES:

1. CENTER OF IMAGE IS OFFSET FROM CENTER OF PACKAGE BY (0.00, 0.10)MM NOMINAL.
2. DIE IS ALIGNED WITHIN +/- 1 DEGREE OF ANY PACKAGE CAVITY EDGE.

Dimensions in: Inches [mm]

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